

256K × 8 ELECTRICALLY ERASABLE EPROM

GENERAL DESCRIPTION

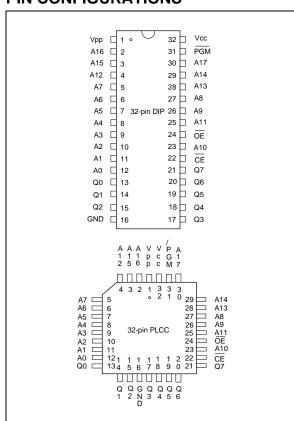
The W27C020M is a high speed, low power Electrically Erasable and Programmable Read Only Memory organized as 262144×8 bits that operates on a single 5 volt power supply. The W27C020M provides an electrical chip erase function. The W27C020M is designed to be used in both 5.0V and 3.3V I/O bus interface environment.

FEATURES

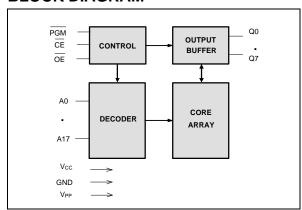
- High speed access time: 70/120 nS (max.)
- Read operating current: 30 mA (max.)
- Erase/Programming operating current: 30 mA (max.)
- Standby current: 1 mA (max.)
- Single 5V power supply

- +14V erase/+12V programming voltage
- Fully static operation
- Output level: 5V/3.3V compatible output
- All inputs and outputs directly TTL/CMOS compatible
- Three-state outputs
- Available packages: 32-pin 600 mil DIP and PLCC

PIN CONFIGURATIONS



BLOCK DIAGRAM



PIN DESCRIPTION

- 1 -

SYMBOL	DESCRIPTION				
A0-A17	Address Inputs				
Q0-Q7	Data Inputs/Outputs				
CE	Chip Enable				
ŌĒ	Output Enable				
PGM	Program Enable				
VPP	Program/Erase Supply Voltage				
Vcc	Power Supply				
GND	Ground				



FUNCTIONAL DESCRIPTION

Read Mode

Like conventional UVEPROMs, the W27C020M has two control functions, both of which produce data at the outputs.

 $\overline{\sf CE}$ is for power control and chip select. $\overline{\sf OE}$ controls the output buffer to gate data to the output pins. When addresses are stable, the address access time (TACC) is equal to the delay from $\overline{\sf CE}$ to output (TCE), and data are available at the outputs TOE after the falling edge of $\overline{\sf OE}$, if TACC and TCE timings are met.

Erase Mode

The erase operation is the only way to change data from "0" to "1." Unlike conventional UVEPROMs, which use ultraviolet light to erase the contents of the entire chip (a procedure that requires up to half an hour), the W27C020M uses electrical erasure. Generally, the chip can be erased within 100 mS by using an EPROM writer with a special erase algorithm.

Erase mode is entered when VPP is raised to VPE (14V), VCC = VCE (5V), \overline{CE} low, \overline{OE} high, A9 = VID (14V), A0 low, and all other address pins low and data input pins high. Pulsing \overline{PGM} low starts the erase operation.

Erase Verify Mode

After an erase operation, all of the bytes in the chip must be verified to check whether they have been successfully erased to "1" or not. The erase verify mode automatically ensures a substantial erase margin. This mode will be entered after the erase operation if VPP = VPE (14V), \overline{CE} low, and \overline{OE} low, \overline{PGM} high.

Program Mode

Programming is performed exactly as it is in conventional UVEPROMs, and programming is the only way to change cell data from "1" to "0." The program mode is entered when VPP is raised to VPP (12V), VCC = VCP (5V), \overline{CE} low, \overline{OE} high, the address pins equal the desired addresses, and the input pins equal the desired inputs. Pulsing PGM low starts the programming operation.

Program Verify Mode

All of the bytes in the chip must be verified to check whether they have been successfully programmed with the desired data or not. Hence, after each byte is programmed, a program verify operation should be performed. The program verify mode automatically ensures a substantial program margin. This mode will be entered after the program operation if VPP = VPP (12V), \overline{CE} low, \overline{OE} low, and \overline{PGM} high.

Erase/Program Inhibit

Erase or program inhibit mode allows parallel erasing or programming of multiple chips with different data. When \overline{CE} high, erasing or programming of non-target chips is inhibited, so that except for the \overline{CE} , the W27C020M may have common inputs.



Standby Mode

The standby mode significantly reduces Vcc current. This mode is entered when \overline{CE} high. In standby mode, all outputs are in a high impedance state, independent of \overline{OE} and \overline{PGM} .

Two-line Output Control

Since EPROMs are often used in large memory arrays, the W27C020M provides two control inputs for multiple memory connections. Two-line control provides for lowest possible memory power dissipation and ensures that data bus contention will not occur.

System Considerations

EPROM power switching characteristics require careful device decoupling. System designers are concerned with three supply current issues: standby current levels (ISB), active current levels (ICC), and transient current peaks produced by the falling and rising edges of $\overline{\text{CE}}$. Transient current magnitudes depend on the device output's capacitive and inductive loading. Two-line control and proper decoupling capacitor selection will suppress transient voltage peaks. Each device should have a 0.1 μF ceramic capacitor connected between its Vcc and GND. This high frequency, low inherent-inductance capacitor should be placed as close as possible to the device. Additionally, for every eight devices, a 4.7 μF electrolytic capacitor should be placed at the array's power supply connection between Vcc and GND. The bulk capacitor will overcome voltage slumps caused by PC board trace inductances.

TABLE OF OPERATING MODES

VPP = 12V, VPE = 14V, VHH = 12V, VCP = 5V, VCE = 5V, VID = 14V, X = VIH or VIL

MODE	PINS							
	CE	OE	PGM	A0	A9	Vcc	VPP	OUTPUTS
Read	VIL	VIL	Х	Х	Х	Vcc	Vcc	Dout
Output Disable	VIL	ViH	Х	Х	Х	Vcc	Vcc	High Z
Standby (TTL)	ViH	Х	Х	Х	Х	Vcc	Vcc	High Z
Standby (CMOS)	Vcc ±0.3V	Х	Х	Х	Х	Vcc	Vcc	High Z
Program	VIL	ViH	VIL	Х	Х	VCP	VPP	DIN
Program Verify	VIL	VIL	ViH	Х	Х	Vcc	VPP	Dout
Program Inhibit	ViH	Х	Х	Х	Х	VCP	VPP	High Z
Erase	VIL	ViH	VIL	VIL	VID	VCE	VPE	FF (Hex)
Erase Verify	VIL	VIL	ViH	Х	Х	Vcc	VPE	Dout
Erase Inhibit	ViH	Х	Х	Х	Х	VCE	VPE	High Z
Product Identifier- manufacturer	VIL	VIL	Х	VIL	Vнн	Vcc	Vcc	DA (Hex)
Product Identifier-device	VIL	VIL	Х	VIH	Vнн	Vcc	Vcc	85 (Hex)



DC CHARACTERISTICS

Absolute Maximum Ratings

PARAMETER	RATING	UNIT
Operation Temperature	0 to +70	°C
Storage Temperature	-65 to +125	°C
Voltage on all Pins with Respect to Ground Except Vcc, VPP and A9 Pins	-0.5 to Vcc +0.5	V
Voltage on Vcc Pin with Respect to Ground	-0.5 to +7	٧
Voltage on VPP Pin with Respect to Ground	-0.5 to +14.5	V
Voltage on A9 Pin with Respect to Ground	-0.5 to +14.5	V

Note: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.

DC Erase Characteristics

 $(TA = 25^{\circ} C \pm 5^{\circ} C, VCC = 5.0V \pm 5\%, VHH = 14V)$

PARAMETER	SYM.	CONDITIONS	LIMITS		UNIT	
			MIN.	TYP.	MAX.	
Input Load Current	ILI	VIN = VIL or VIH	-10	-	10	μΑ
Vcc Erase Current	ICP	$\overline{CE} = VIL, \overline{OE} = VIH,$	-	-	30	mA
		PGM = VIL, A9 = VHH				
VPP Erase Current	IPP	CE = VIL, OE = VIH,	-	-	30	mA
		PGM = VIL, A9 = VHH				
Input Low Voltage	VIL	-	-0.3	-	8.0	V
Input High Voltage	VIH	-	2.4	-	5.5	V
Output Low Voltage (Verify)	Vol	IOL = 2.1 mA	-	-	0.45	V
Output High Voltage (Verify)	Vон	Iон = -0.4 mA	2.4	-	-	V
	VOH2	IOH = -0.1 mA, Vcc = 5V	-	-	3.8	V
A9 Erase Voltage	VID	-	13.75	14.0	14.25	V
VPP Erase Voltage	VPE	-	13.75	14.0	14.25	V
Vcc Supply Voltage (Erase)	VCE	-	4.75	5.0	5.25	V

Note: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP.



CAPACITANCE

 $(Vcc = 5V, TA = 25^{\circ} C, f = 1 MHz)$

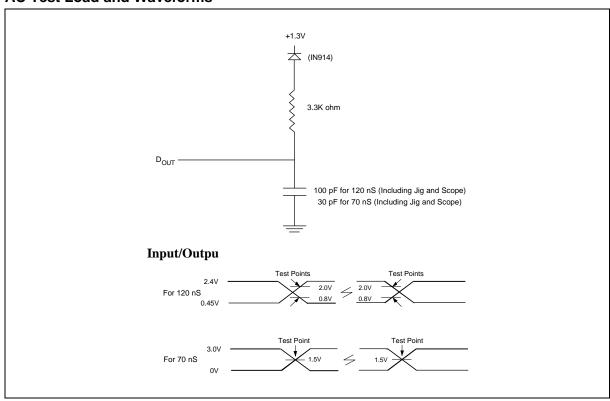
PARAMETER	SYMBOL	CONDITIONS	MAX.	UNIT
Input Capacitance	CIN	VIN = 0V	6	pF
Output Capacitance	Соит	Vout = 0V	12	pF

AC CHARACTERISTICS

AC Test Conditions

PARAMETER	CONDITIONS		
	70 nS	120 nS	
Input Pulse Levels	0 to 3.0V	0.45V to 2.4V	
Input Rise and Fall Times	5 nS	10 nS	
Input and Output Timing Reference Level	1.5V/1.5V	0.8V/2.0V	
Output Load	CL = 30 pF, IOH/IOL = -0.4 mA/2.1 mA	CL = 100 pF, IOH/IOL = -0.4 mA/2.1 mA	

AC Test Load and Waveforms





READ OPERATION DC CHARACTERISTICS

 $(Vcc = 5.0V \pm 5\%)$

PARAMETER	SYM.	M. CONDITIONS LIMI		LIMITS		UNIT
			MIN.	TYP.	MAX.	
Input Load Current	ILI	VIN = 0V to VCC	-5	-	5	μΑ
Output Leakage Current	ILO	Vout = 0V to Vcc	-10	-	10	μΑ
Standby Vcc Current (TTL input)	ISB	CE = VIH	-	-	1.0	mA
Standby Vcc Current (CMOS input)	ISB1	CE = Vcc ±0.3V	-	5	100	μΑ
Vcc Operating Current	Icc	CE = VIL IOUT = 0 mA f = 5 MHz	-	-	30	mA
VPP Operating Current	lpp	VPP = VCC	-	-	10	μΑ
Input Low Voltage	VIL	-	-0.3	-	0.8	V
Input High Voltage	VIH	-	2.2	-	Vcc +0.5	V
Output Low Voltage	Vol	IOL = 2.1 mA	-	-	0.45	V
Output High Voltage	Vон	IOH = -0.4 mA	2.4	-	-	V
	VOH2	IOH = -0.1 mA	-	-	3.8	V
VPP Operating Voltage	VPP	-	Vcc -0.7	-	Vcc	V

READ OPERATION AC CHARACTERISTICS

(Vcc = 5.0V \pm 5%, for 70 and 120 nS; TA = 0 to 70° C)

PARAMETER	SYM.	W27C020M-70		W27C0	UNIT	
		MIN.	MAX.	MIN.	MAX.	
Read Cycle Time	Trc	70	-	120	-	nS
Chip Enable Access Time	TCE	-	70	-	120	nS
Address Access Time	TACC	-	70	-	120	nS
Output Enable Access Time	TOE	-	30	-	55	nS
OE High to High-Z Output	TDF	-	25	-	30	nS
Output Hold from Address Change	Тон	0	-	0	-	nS

Note: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP.



DC PROGRAMMING CHARACTERISTICS

 $(VCC = 5.0V \pm 5\%, TA = 25^{\circ} C \pm 5^{\circ} C)$

PARAMETER	SYM.	CONDITIONS	NDITIONS LIMITS			UNIT
			MIN.	TYP.	MAX.	
Input Load Current	ILI	VIN = VIL or VIH	-	-	±10	μΑ
Vcc Program Current	ICP	$\overline{CE} = VIL, \overline{OE} = VIH,$	-	-	30	mA
		PGM = VIL				
VPP Program Current	IPP	$\overline{CE} = VIL, \overline{OE} = VIH,$	-	-	30	mA
		PGM = VIL				
Input Low Voltage	VIL	-	-0.3	-	0.8	V
Input High Voltage	ViH	-	2.4	-	5.5	V
Output Low Voltage (Verify)	Vol	IOL = 2.1 mA	-	-	0.45	V
Output High Voltage (Verify)	Vон	Iон = -0.4 mA	2.4	-	ı	V
	VOH2	Iон = -0.1mA	-	-	3.5	V
A9 Silicon I. D. Voltage	VID	-	11.5	12.0	12.5	V
VPP Program Voltage	VPP	-	11.75	12.0	12.25	V
Vcc Supply Voltage (Program)	VCP	-	4.75	5.0	5.25	V

AC PROGRAMMING/ERASE CHARACTERISTICS

 $(VCC = 5.0V \pm 5\%, TA = 25^{\circ} C \pm 5^{\circ} C)$

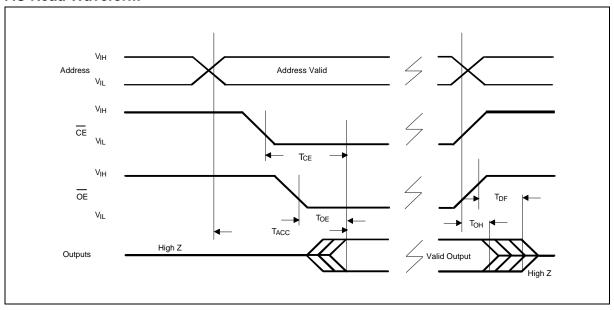
PARAMETER	SYM.	LIMITS			UNIT
		MIN.	TYP.	MAX.	
VPP Setup Time	Tvps	2.0	-	-	μS
Address Setup Time	Tas	2.0	1	-	μS
Data Setup Time	TDS	2.0	1	-	μS
PGM Program Pulse Width	TPWP	95	100	105	μS
PGM Erase Pulse Width	TPWE	95	100	105	mS
Data Hold Time	TDH	2.0	-	-	μS
OE Setup Time	Toes	2.0	-	-	μS
Data Valid from OE	TOEV	-	-	150	nS
OE High to Output High Z	TDFP	0	-	130	nS
Address Hold Time after PGM High	Тан	0	-	-	μS
Address Hold Time (Erase)	TAHE	2.0	-	-	μS
CE Setup Time	TCES	2.0	-	-	μS

Note: Vcc must be applied simultaneously or before VPP and removed simultaneously or after VPP.

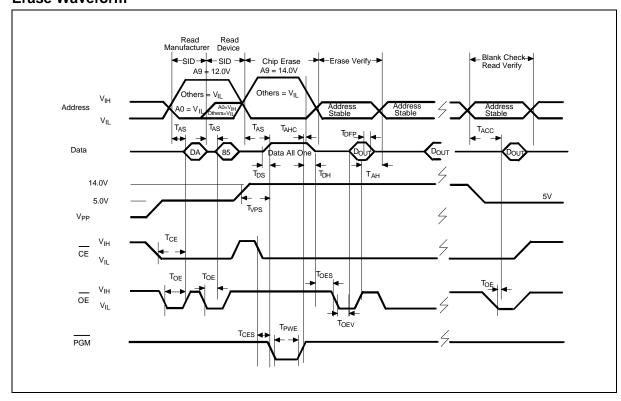


TIMING WAVEFORMS

AC Read Waveform



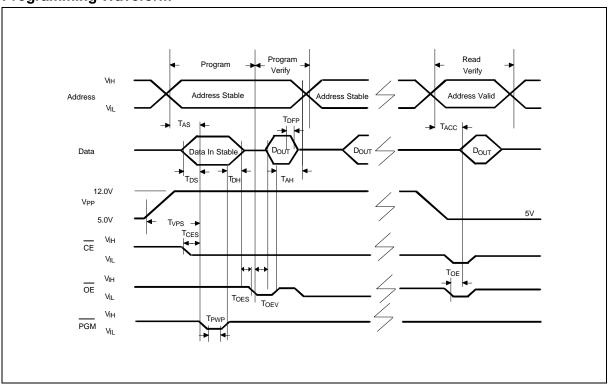
Erase Waveform





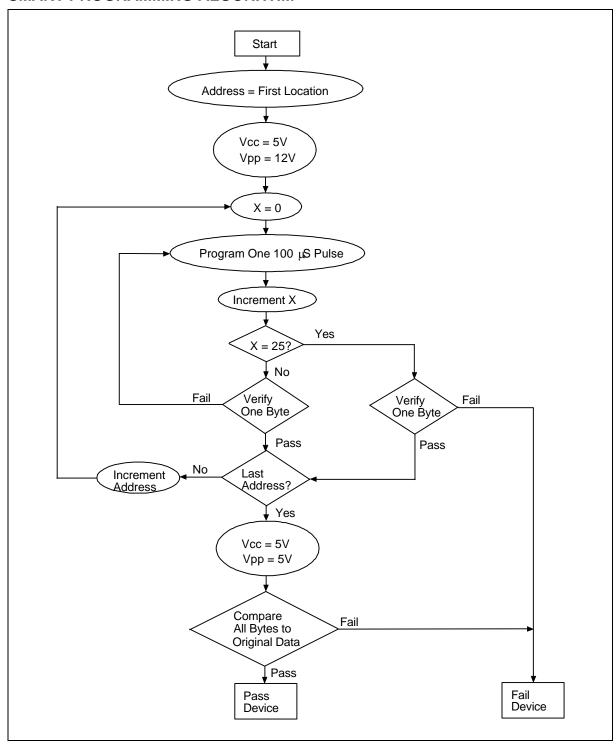
Timing Waveforms, continued

Programming Waveform



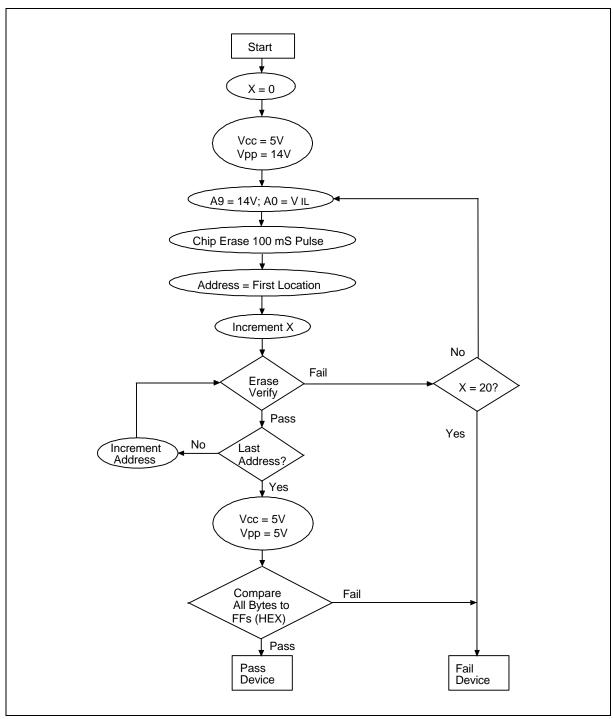


SMART PROGRAMMING ALGORITHM





SMART ERASE ALGORITHM





ORDERING INFORMATION

PART NO.	ACCESS TIME (nS)	POWER SUPPLY CURRENT MAX. (mA)	STANDBY Vcc CURRENT MAX. (mA)	PACKAGE
W27C020M-70	70	30	100	600 mil DIP
W27C020M-12	120	30	100	600 mil DIP
W27C020MP-70	70	30	100	32-pin PLCC
W27C020MP-12	120	30	100	32-pin PLCC

Notes:

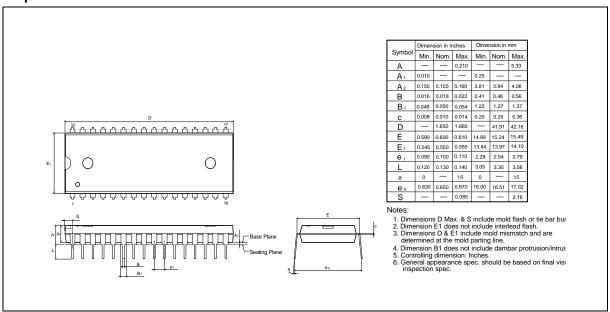
^{1.} Winbond reserves the right to make changes to its products without prior notice.

^{2.} Purchasers are responsible for performing appropriate quality assurance testing on products intended for use in applications where personal injury might occur as a consequence of product failure.

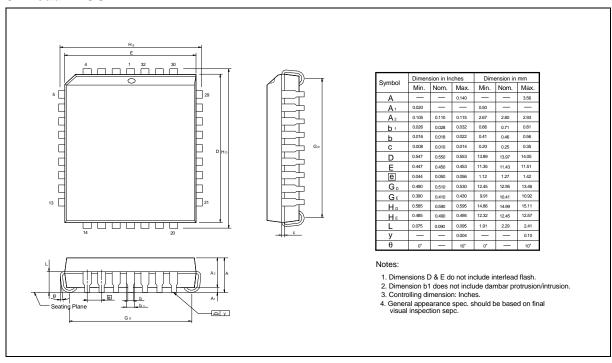


PACKAGE DIMENSIONS

32-pin P-DIP



32-Lead PLCC





VERSION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
A1	Mar. 1999	-	Initial Issued
A2	Jun. 1999	1, 5, 6, 12	Delete 90 nS bining



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Note: All data and specifications are subject to change without notice.